MA2Z360J (MA360J)

Silicon epitaxial planar type

For UHF and VHF electronic tuners

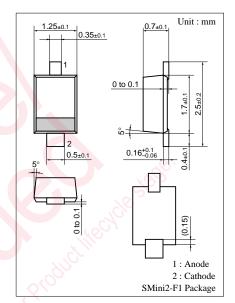
■ Features

- Large capacitance ratio
- Small series resistance r_D

\blacksquare Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage (DC)	V_R	30	V	
Peak reverse voltage*	V_{RM}	35	V	
Forward current (DC)	I_{F}	20	mA	
Junction temperature	Tj	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	

Note) *: $R_L = 10 \text{ k}\Omega$



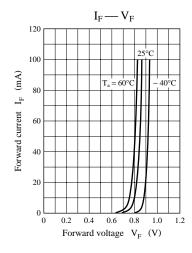
Marking Symbol: 6A

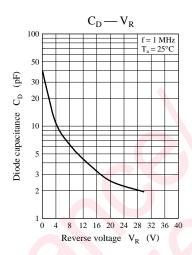
■ Electrical Characteristics T_a = 25°C

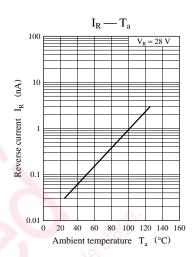
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current (DC)	I_R	$V_R = 28 \text{ V}$	150		10	nA
Diode capacitance	C _{D(2V)}	V _R = 2 V, f = 1 MHz	14.360		16.340	pF
	C _{D(25V)}	V _R = 25 V, f = 1 MHz	2.089		2.448	pF
	C _{D(10V)}	$V_R = 10 \text{ V, f} = 1 \text{ MHz}$	5.433		6.369	pF
inte	C _{D(17V)}	$V_R = 17 V, f = 1 MHz$	2.945		3.452	pF
Capacitance ratio	C _{D(2V)} /C _{D(25V)}	84. 1/4.	5.95		7.26	_
Diode capacitance deviation	ΔC	$C_{D(2V)(10V)(17V)(25V)}$			2	%
Series resistance*	r_{D}	$C_D = 9 \text{ pF, f} = 470 \text{ MHz}$			0.6	Ω

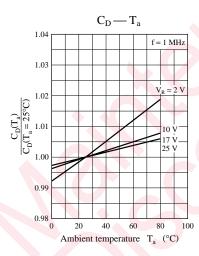
Note) 1. Rated input/output frequency: 470 MHz

^{2. *:} r_f measuring instrument: YHP MODEL 4191A RF IMPEDANCE ANALYZER









Panasonic 323

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